



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



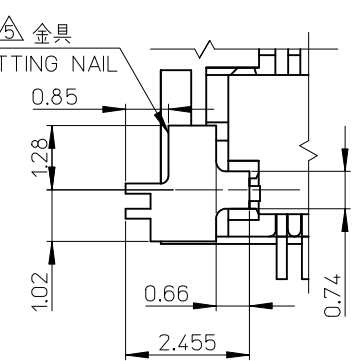
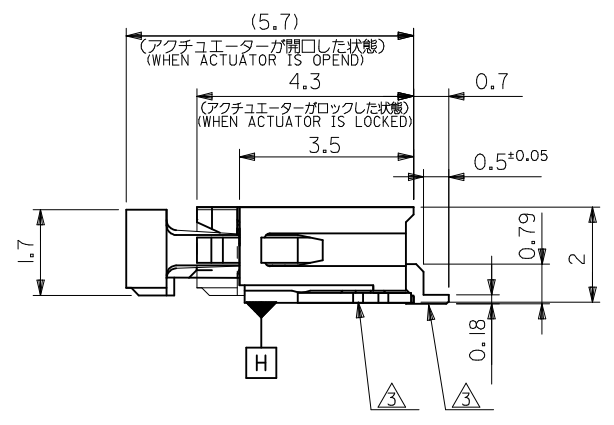
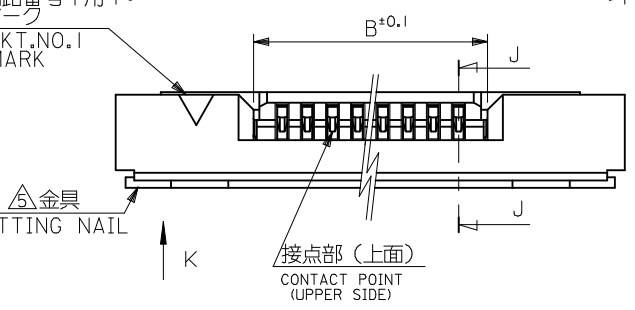
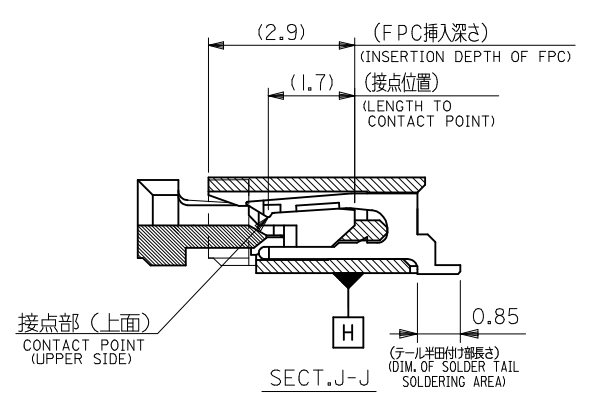
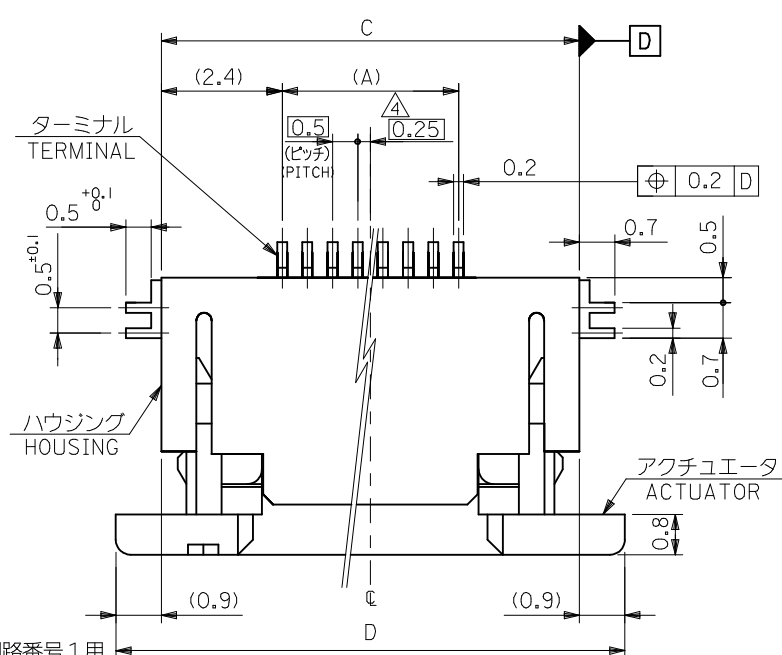
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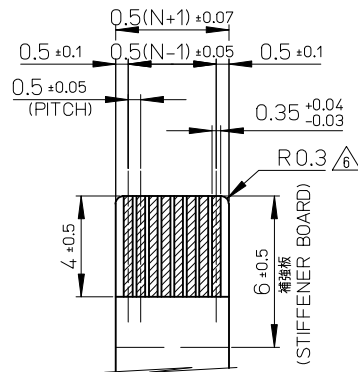




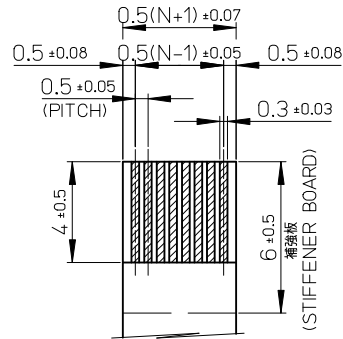
16.1	14.3	10.65	9.5	52745-2090	20
15.6	13.8	10.15	9	52745-1990	19
14.1	12.3	8.65	7.5	52745-1690	16
13.6	11.8	8.15	7	52745-1590	15
12.6	10.8	7.15	6	52745-1390	13
11.6	9.8	6.15	5	52745-1190	11
11.1	9.3	5.65	4.5	52745-1090	10
10.6	8.8	5.15	4	52745-0990	9
10.1	8.3	4.65	3.5	52745-0890	8
9.6	7.8	4.15	3	52745-0790	7
9.1	7.3	3.65	2.5	52745-0690	6
8.1	6.3	2.65	1.5	52745-0490	4
D	C	B	(A)	EMBOSSED PACKAGE ORDER No. オーダー番号	極数 CKT.

CONNECTOR SERIES NO. : 52745-\*\*17  
SCALE 10:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION

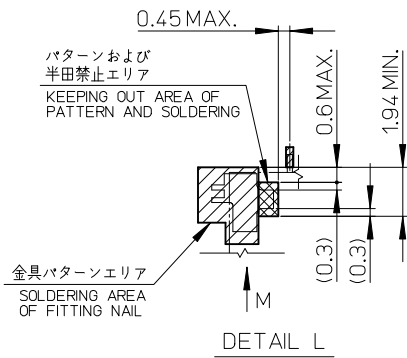
REVISED EC NO: J2016-0389 DRWN: MORISHITA 2015/10/20 CHKD: TAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	TITLE 0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING <b>molex</b> DOCUMENT NO. SD-52745-054 SHEET NO. 1 OF 2
	0.25 UNDER UNDER ±0.03 0.25 OVER 0.5 UNDER ±0.05 0.5 OVER 1.0 UNDER ±0.1 1.0 OVER 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3	DRAWN BY SAIHARA DATE 1994/03/24 CHECKED BY SKUNISHI DATE 2000/06/30 APPROVED BY KMORIKAWA DATE 2010/07/16	SEE CHART		
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.	
	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



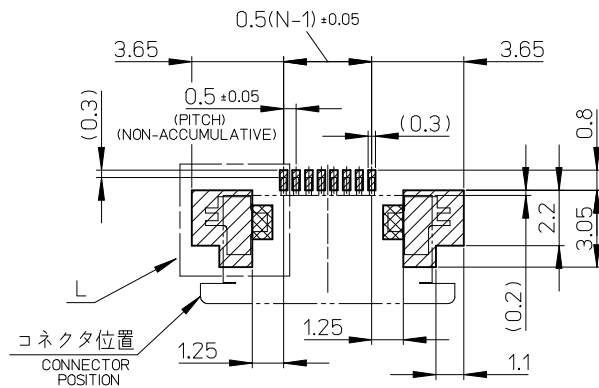
適合金めっきFPC推奨寸法  
 APPLICABLE FPC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3+0.03/-0.03



適合金めっきFFC推奨寸法  
 APPLICABLE FFC OF GOLD  
 PLATING RECOMMENDED DIMENSION  
 仕上がり厚さ: 0.3±0.03  
 THICKNESS: 0.3+0.03/-0.03



VIEW M  
 (DETAIL OF FITTING NAIL  
 ON PATTERN)



参考基板レイアウト  
 (マウント面)  
 RECOMMENDED P.C.BOARD  
 PATTERN DIMENSION(REF.)  
 (MOUNTING SIDE)

注記NOTES

1.使用材料

MATERIAL

- ハウジング: 46ナイロン、ガラス充填、UL94V-0、白
- HOUSING: PA46, GLASS FILLED, UL94V-0, WHITE
- アクチュエータ: ポリフェニレンサルファイド (PPS)、ガラス充填、UL94V-0、黒
- ACTUATOR: POLYPHENYLENE SULFIDE, GLASS FILLED, UL94V-0, BLACK
- ターミナル: リン青銅、銅下地半田めっき (t=0.2)
- TERMINAL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING
- 金具: リン青銅、銅下地半田めっき (t=0.2)
- FITTING NAIL: PHOSPHOR BRONZE, TIN-LEAD OVER COPPER PLATING

2.エンボステープ梱包時は、アクチュエータがロックした状態になります。

IN THE PACKAGE, ACTUATOR OF PART  
 NO.52745-\*\*17 SHOULD BE LOCKED.

3.

ソルダータール半田付け面のズレ量、及び金具半田付け面のズレ量は、  
 基準面Hに対して上方向に0.1MAXIMUM、下方向0.15MAXIMUMとする。  
 MISALIGNMENT OF SOLDER TAILS AND FITTING NAILS FROM  
 DATUM-H.  
 UPPER DIRECTION: 0.1 MAXIMUM  
 LOWER DIRECTION: 0.15 MAXIMUM

4.

偶数極に適用  
 APPLY FOR EVEN CIRCUIT.

5.

ハターン剥離止め金具

FITTING NAIL FOR PREVENTION OF PEELING OF P.W.B. PATTERN.

6.

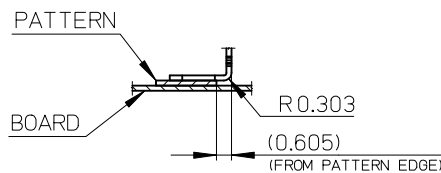
R0.3は、FPCの胴体部にかからないこと  
 R0.3 MUST NOT BE OVERLAPED TO PATTERN OF FPC.

FPCについて:

打抜き方向は導体側から補強板を推奨致します。  
 補強フィルム材質はポリイミドを推奨致します。  
 接着剤は熱硬化接着剤を推奨致します。

ABOUT FPC:

RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.  
 RECOMMENDED MATERIAL :  
 STIFFENER FILM : POLYIMIDE  
 BONDING AGENT : THERMOSETTING BONDING AGENT



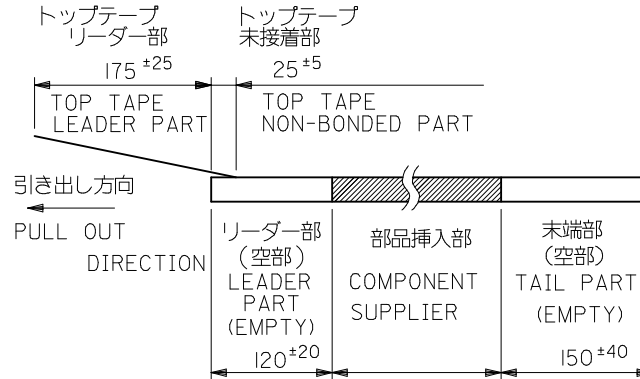
REVISED	EC NO: J2016-0389	DRWN: MORISHITA 2015/10/20	CHKD: TAKAHASHI 2015/10/20	APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
					0.25 UNDER UNDER ±0.03	0.25 OVER 0.5 UNDER ±0.05	0.5 OVER 1.0 UNDER ±0.1	MM ONLY	5:1	METRIC		
K	REV	DESCRIPTION	1.0 OVER 10 UNDER ±0.2	10 OVER 30 UNDER ±0.25	30 OVER ±0.3	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SIZE	DATE	TITLE	0.5 FPC CONN. ZIF FOR SMT R/A (UPPER CONTACT) TIN-LEAD PLATING	
			A3	1994/03/24	2000/06/30	2010/07/16	SEE SHEET 1	SD-52745-054				

注記 NOTES

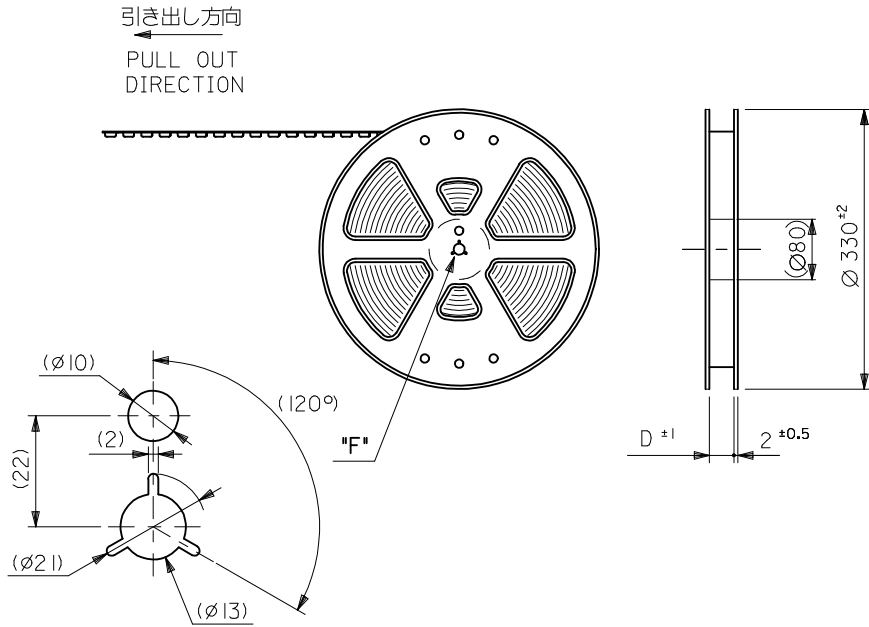
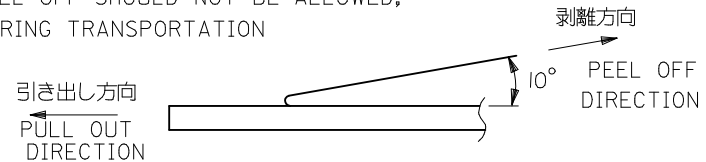
1. 製品番号 52745-\*\*17 の梱包状態はアクチュエータがロックした状態とする。  
 詳細寸法については図面 SD-52745-054 を参照下さい。  
 IN THE PACKAGE,ACTUATOR OF PART NO.52745-\*\*17 SHOULD BE LOCKED  
 RE DETAILED DIMENSIONS,SEE SD-52745-054

2. 梱包数量：1000個/リール  
 NUMBER OF CONNECTORS:1000PCS/REEL

3. リードテープ長さ LEAD TAPE LENGTH



4. トップテープの剥離強度：(剥離方向は下図参照)  
 0.1N~0.7N(10.2gf~71.4gf) 尚、本規格値は、出荷時に適用。  
 (但し、輸送時に剥離が発生しない事。)  
 PEELING OFF FORCE OF TOP TAPE  
 0.1N~0.7N(10.2gf~71.4gf)(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)  
 THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT  
 PEEL OFF SHOULD NOT BE ALLOWED,  
 DURING TRANSPORTATION

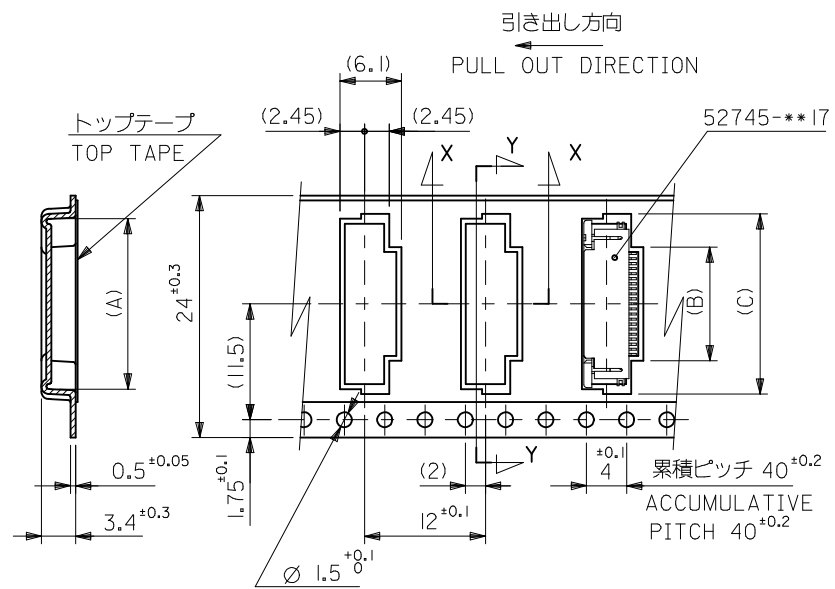


DETAIL "F"

5. 材料 キャリアテープ：ポリプロピレン (PP)  
 トップテープ：PET, PE, PEF  
 リール：ポリスチレン (PS) <リサイクル材を含む>

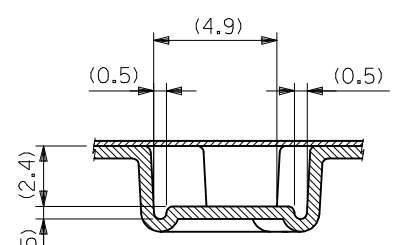
MATERIAL CARRIER TAPE:POLYPROPYLENE  
 TOP TAPE:PET,PE,PEF  
 REEL:POLYSTYREN(PS)  
 <RECYCLE MATERIAL CONTAINED>

REVISED EC NO: J2016-0389 DRWN:IMORISHITA 2015/10/20 CHKD:KTAKAHASHI 2015/10/20 APPR:YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	MTAKAHASHI	04 2013/07/30	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (1/3)		
	0.5 OVER	1.0 UNDER	±0.1	KTAKAHASHI	2013/07/30	molex		
1.0 OVER	10 UNDER	±---	APPROVED BY	DATE	DOCUMENT NO.			
10 OVER	30 UNDER	±---	YNOGAWA	2013/11/07	SD-52745-057			
30 OVER		±---	MATERIAL NO.		SHEET NO.			
ANGULAR	±---	°	SEE SHEET 1		1 OF 3			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			



SECT.Y-Y

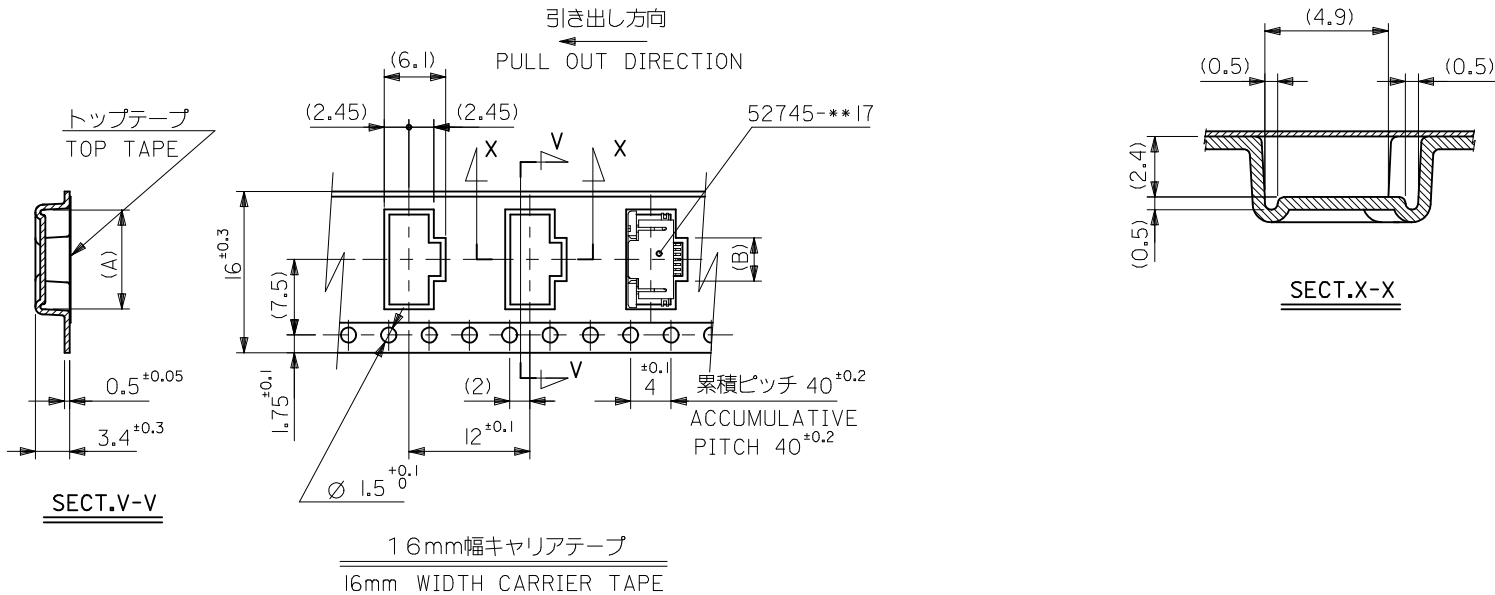
24mm幅キャリアテープ  
24mm WIDTH CARRIER TAPE



SECT.X-X

24	25.5	17.4	10.8	16.4	52745-2090	20	
		16.9	10.3	15.9	-1990	19	
		15.4	8.8	14.4	-1690	16	
		14.9	8.3	13.9	-1590	15	
		13.9	7.3	12.9	-1390	13	
		12.9	6.3	11.9	-1190	11	
		12.4	5.8	11.4	-1090	10	
		11.9	5.3	10.9	-0990	9	
		11.4	4.8	10.4	-0890	8	
		10.9	4.3	9.9	-0790	7	
10.4	3.8	9.4	52745-0690	6			
キャリアテープ幅 CARRIER TAPE IDTH		D	(C)	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2016-0389 DRWN: MORISHITA 2015/10/20 CHKD: TAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	MTAKAHASHI	104 2013/07/30	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (2/3)		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE	<b>molex</b> DOCUMENT NO. SD-52745-057 SHEET NO. 2 OF 3		
	1.0 OVER	10 UNDER	±---	KTAKAHASHI	2013/07/30			
10 OVER	30 UNDER	±---	APPROVED BY	DATE	SEE CHART			
30 OVER		±---	YNOGAWA	2013/11/07	MATERIAL NO.			
ANGULAR	±---	°	SIZE A3			THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								



16	17.5	2.8	8.4	52745-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	(B)	(A)	ENG. NO.	極数 CIRCUIT

REVISED EC NO: J2016-0389 DRWN: TMORISHITA 2015/10/20 CHKD: KTAKAHASHI 2015/10/20 APPR: YNOGAWA 2015/11/13	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±0.03	DRAWN BY	DATE	TITLE		
	0.25 OVER	0.5 UNDER	±0.05	MTAKAHASHI	104 2013/07/30	0.5 FPC CONN ZIF SMT RA UPPER CONTACT EMBSTP PKG (3/3)		
	0.5 OVER	1.0 UNDER	±0.1	CHECKED BY	DATE			
	1.0 OVER	10 UNDER	±---	KTAKAHASHI	2013/07/30			
30 OVER	30 UNDER	±---	APPROVED BY	DATE	SD-52745-057	3 OF 3		
ANGULAR	±---	°	YNOGAWA	2013/11/07	SEE CHART			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			